

This listing of claims will replace all prior versions, and listing, of claims in the application:

**Listing of Claims:**

~~1.A~~ (Currently Amended) An opto-electronic package comprising the combination of:

<sup>12, 14</sup>  
an enclosed package;

<sup>58'</sup>  
a plurality of electrical contacts extending into the enclosed package;

an optical ~~integrated circuit~~ <sup>C</sup> device mounted within the package and coupled to the electrical contacts; and

<sup>P</sup>  
an optical fiber extending through at least one peripheral portion of the package to the optical ~~integrated circuit~~ device along a common plane;

<sup>12, 14</sup>  
wherein the package is comprised of opposite portions joined together at an interface substantially at the common plane and forming a hermetic enclosure. → Cols 5 Lns 15-34

A2  
(2) (Original) An opto-electronic package according to claim 1, further including a second optical fiber extending through a second peripheral portion of the package along the common plane.

~~3.~~ <sup>A+B</sup> (Original) An opto-electronic package according to claim 1, wherein the optical fiber comprises a plurality of <sup>B-27</sup> optical fibers.

~~4.~~ <sup>A+B</sup> (Currently Amended) An opto-electronic package according to claim 1, wherein the optical fiber comprises plural optical fibers extending through opposite ends at least one side of the package ~~to the optical integrated circuit~~ into the enclosed package along the common plane.

(5) (Original) An opto-electronic package according to claim 4, wherein the plural optical fibers comprise opposite arrays of optical fibers lying within the common plane.

6. ~~A13~~ (Currently Amended) An opto-electronic package according to claim 4, <sup>A12 B10</sup> ~~where wherein~~ the opposite portions of the package comprise a package body and a package lid joined at <sup>A14 B12</sup> ~~said interface~~ and configured to form end pipes around the optical fibers at ~~opposite ends~~ <sup>A32 B24</sup> at least one side of the package.

7. ~~A13~~ (Currently Amended) An opto-electronic package according to claim 6, wherein the package body and the package lid are solder sealed to each other along said interface and the optical fibers are solder sealed <sup>B Col 22 n 56-65</sup> ~~with the end pipes at the opposite ends of the package to the package body and the package lid to create a fully hermetic package.~~

8. ~~A13~~ (Currently Amended) An opto-electronic package according to claim 6, wherein the package body has plural grooves therein at ~~opposite ends thereof forming portions of the end pipes.~~ <sup>B24</sup>

9. <sup>A2</sup> ~~A13~~ (Currently Amended) An opto-electronic package comprising the combination of:

<sup>A12</sup> a package body having electrical leads extending through at least one side thereof to wire bond pads <sup>A2</sup> within the body, and a fiber feedthrough path <sup>A32</sup> extending through the package body from ~~opposite ends~~ at least one side thereof;

<sup>A12</sup> an optical ~~integrated circuit device~~ <sup>A58</sup> mounted in the package body in the fiber feedthrough paths and coupled to the wire bond pads;

<sup>A12</sup> a pair of at least one <sup>AP</sup> fiber arrays <sup>B27</sup> array extending into the package body from ~~the opposite ends~~ at least one side thereof along the fiber feedthrough path ~~to opposite sides of the optical integrated circuit;~~ and

<sup>A12</sup> a package lid mounted on and enclosing the package body and having <sup>A12</sup> ~~opposite at least one feedthrough portions~~ portion disposed at the fiber feedthrough path.

10. ~~A13~~ (Original) An opto-electronic package according to claim 9, wherein the fiber feedthrough path lies within a common plane within an interface between the package lid and the package body. <sup>A</sup>

~~11. (Original) An opto-electronic package according to claim 10, wherein the package lid is solder sealed to the package body around the interface therebetween.~~ *PAB*

~~12. (Currently Amended) An opto-electronic package according to claim 9, wherein the package body and the package lid each have hollowed-out fiber feedthrough portions ~~at opposite ends thereof~~ disposed on opposite sides of the at least one fiber arrays array and forming an end pipes pipe.~~ *A32 B24*

~~13. (Currently Amended) An opto-electronic package according to claim 12, wherein the ~~pair of~~ at least one fiber arrays ~~are~~ array is solder sealed within the end ~~pipes pipe~~.~~ *B*

*A2* ~~14. (Currently Amended) An opto-electronic package according to claim 12, wherein the hollowed-out fiber feedthrough portions of the package body each have a plurality of grooves therein for receiving individual fibers of the ~~pair of~~ fiber arrays at least one fiber array.~~ *B 24*

*same as 9*  
~~15. (Currently Amended) A method of making an opto-electronic package comprising the steps of:~~

*method* ~~providing a package body having fiber feedthrough paths on opposite sides of an optical integrated circuit at least one side thereof;~~

~~laying optical fibers in the fiber feedthrough paths ~~on the opposite sides of the optical integrated circuit, aligning the optical fiber and attaching the optical fibers to the optical integrated circuit~~ of the package body;~~

~~providing a package lid having fiber feedthrough ~~paths at opposite ends thereof~~ portions disposed at the fiber feedthrough paths;~~

~~mounting the package lid on the package body so that the fiber feedthrough paths thereof are disposed on opposite sides of the optical fibers from the fiber feedthrough paths of the package body and pipes are formed around the fiber arrays;~~

~~sealing the package lid to the package body; and  
sealing the optical fibers with the fiber feedthrough paths of to the  
package body and the package lid to form a hermetic enclosure.~~

16. (Currently Amended) A method of making a opto-electronic package according to claim 15, comprising the further step of anchoring the optical fibers at ~~the fiber feedthrough paths~~ within the end pipes of the package body and the package lid.

17. (Original) A method of making an opto-electronic package according to claim 15, wherein the steps of sealing the package lid and sealing the optical fibers are performed as a single step.

18. (New) An opto-electronic package according to claim 4, wherein the plural optical fibers extend through opposite sides of the package into the enclosed package along the common plane.

19. (New) An opto-electronic package according to claim 4, wherein the plural optical fibers extend through adjacent sides of the package into the enclosed package along the common plane.

20. (New) An opto-electronic package according to claim 6, wherein the package body and the package lid are configured to form end pipes around optical fibers at opposite sides of the package.

21. (New) An opto-electronic package according to claim 6, wherein the package body and the package lid are configured to form end pipes at adjacent sides of the package.

22. (New) An opto-electronic package according to claim 9, wherein the package has a plurality of fiber arrays.

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Cont.

(23) (New) An opto-electronic package according to claim 22, wherein the plurality of fiber arrays extend into the package body from different sides thereof.

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